Description

JMT N-channel Enhancement Mode Power MOSFET

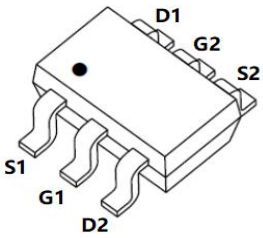
Features

- 20V, 0.9A
  $R_{DS(ON)}$< 175mΩ @ V_{GS}=4.5V
  $R_{DS(ON)}$< 275mΩ @ V_{GS}=2.5V
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired
- ESD Protected: 2KV

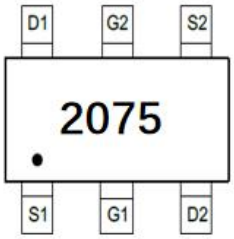
Application

- Load Switch
- PWM Application
- Power management

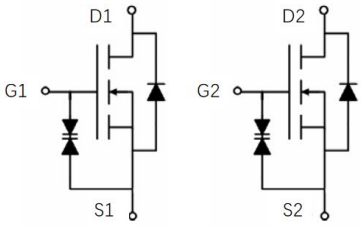
RoHS



SOT-363-6L（Dual）top view



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
2075	JMTLB3134K	TAPING	SOT-363-6L	7inch	3000	120000

Absolute Maximum Ratings (T_A=25℃ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		20	V
V_{GSS}	Gate-Source Voltage		±10	V
I_D	Continuous Drain Current	T_A= 25℃	0.9	A
		T_A= 100℃	0.6	A
I_{DM}	Pulsed Drain Current note1		3.6	A
P_D	Power Dissipation	T_A= 25℃	0.23	W
$R_{\theta JA}$	Thermal Resistance, Junction to Case		543	℃/W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	℃

Electrical Characteristics (T_J=25℃ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250μA	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=20V, V_{GS}=0V,	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS}=0V, V_{GS}= ±10V	-	-	±10	uA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250μA	0.4	0.7	1.0	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note2	V_{GS}=4.5V, I_D=0.5A	-	135	240	mΩ
		V_{GS}=2.5V, I_D=0.4A	-	195	280	
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS}=10V, V_{GS}=0V, f=1.0MHz	-	60	-	pF
C_{oss}	Output Capacitance		-	22	-	pF
C_{rss}	Reverse Transfer Capacitance		-	12	-	pF
Q_g	Total Gate Charge	V_{DS}=10V, I_D=0.9A, V_{GS}=4.5V	-	1	-	nC
Q_{gs}	Gate-Source Charge		-	0.28	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	0.22	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	V_{DS}=10V, I_D=0.5A, R_{GEN}=10Ω, V_{GS}=4.5V	-	2	-	ns
t_r	Turn-on Rise Time		-	19	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	10	-	ns
t_f	Turn-off Fall Time		-	23	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	0.9	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	3.6	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS}=0V, I_S=0.9A	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

Figure1: Output Characteristics

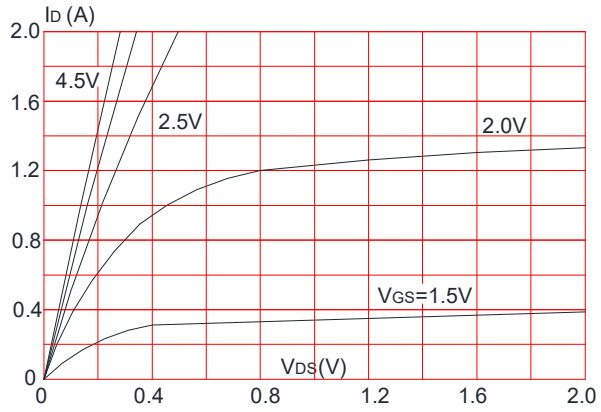


Figure 2: Typical Transfer Characteristics

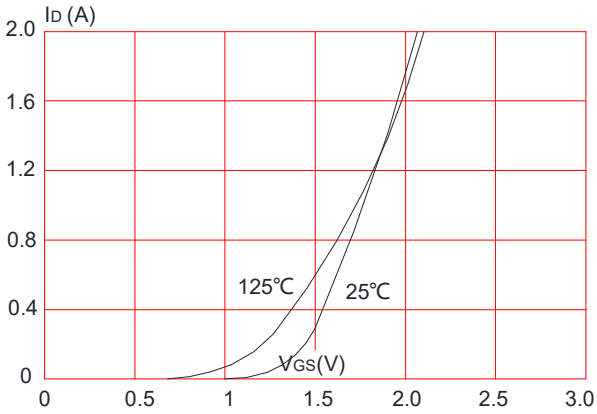


Figure 3: On-resistance vs. Drain Current

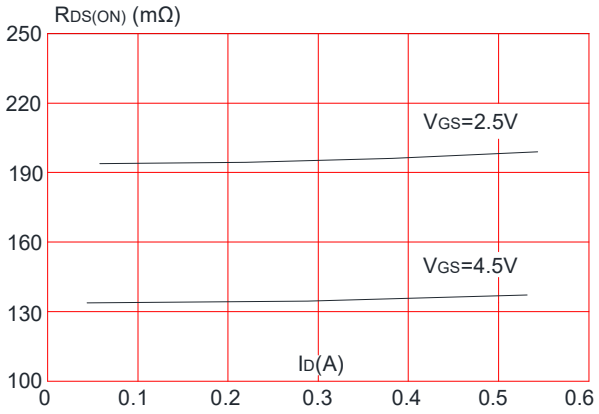


Figure 4: Body Diode Characteristics

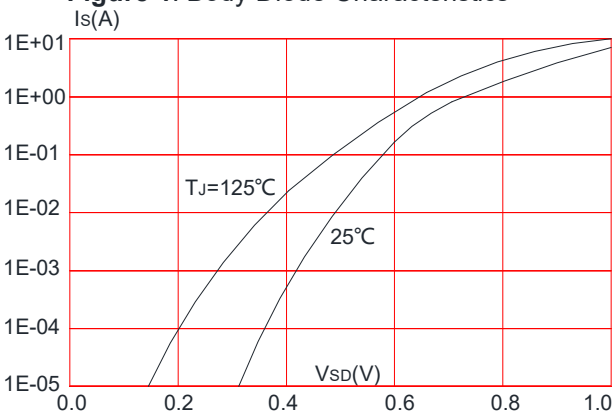


Figure 5: Gate Charge Characteristics

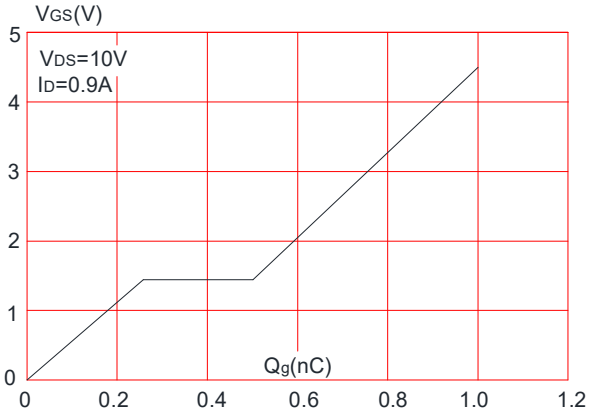


Figure 6: Capacitance Characteristics

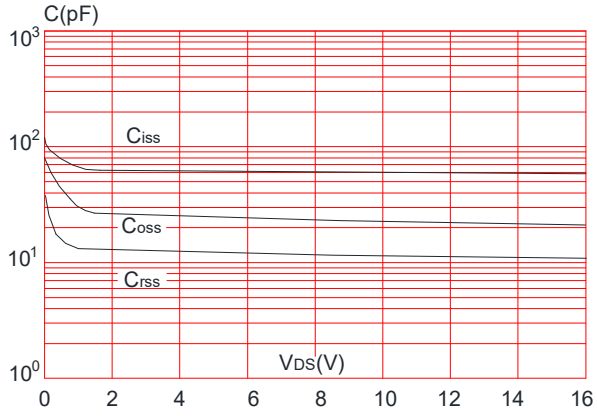


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

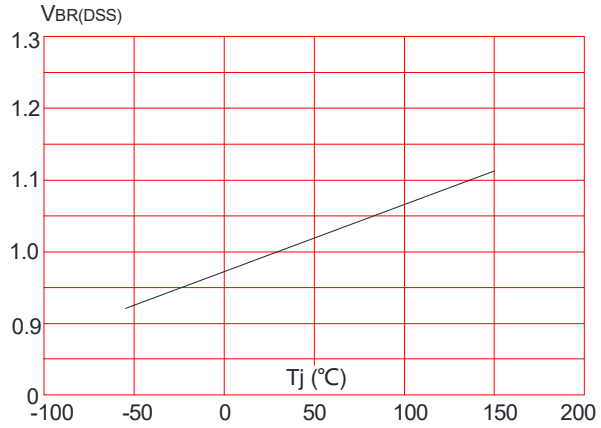


Figure 8: Normalized on Resistance vs. Junction Temperature

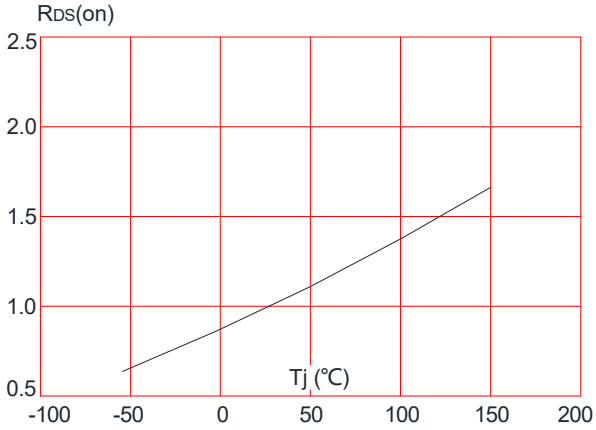


Figure 9: Maximum Safe Operating Area

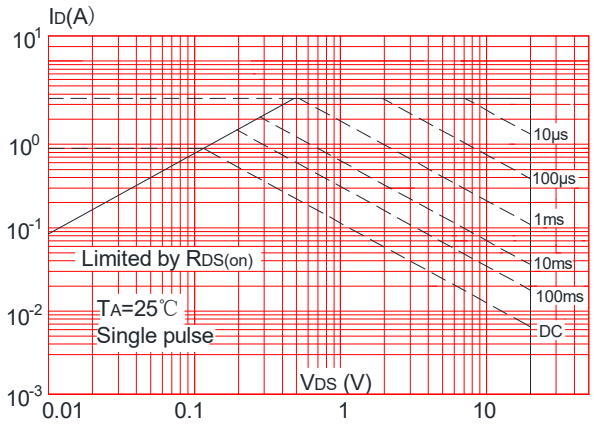


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

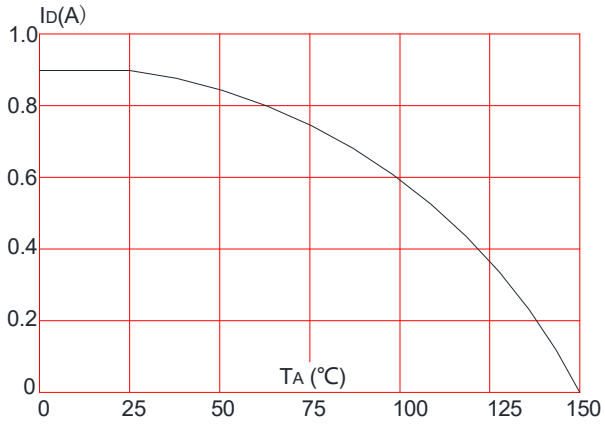
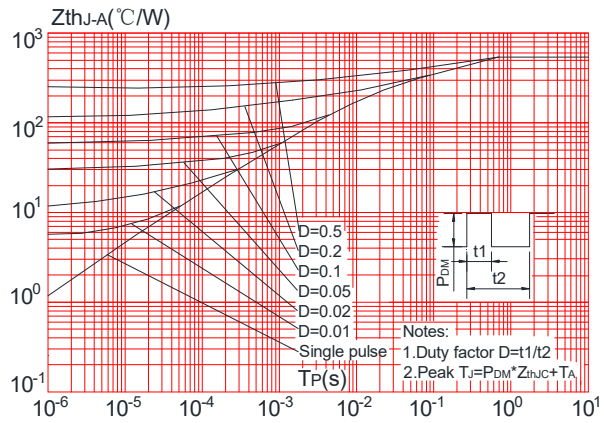


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Test Circuit

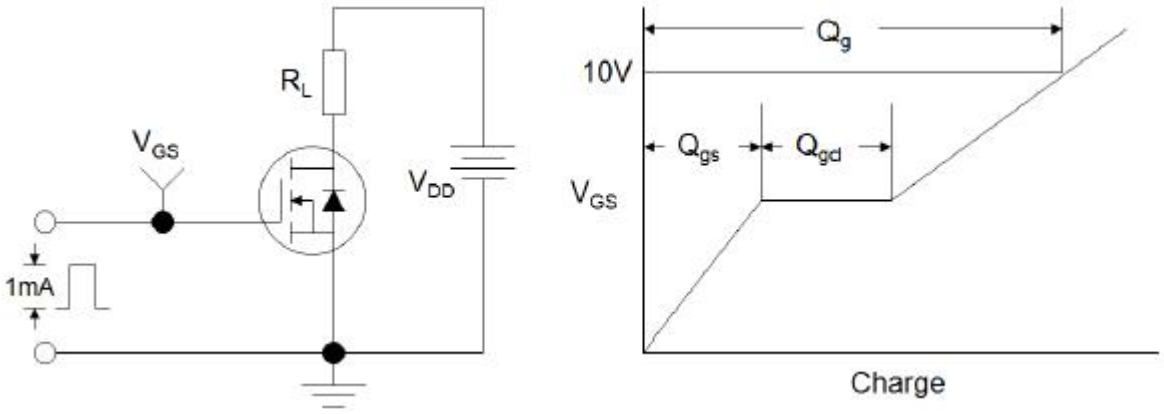


Figure1:Gate Charge Test Circuit & Waveform

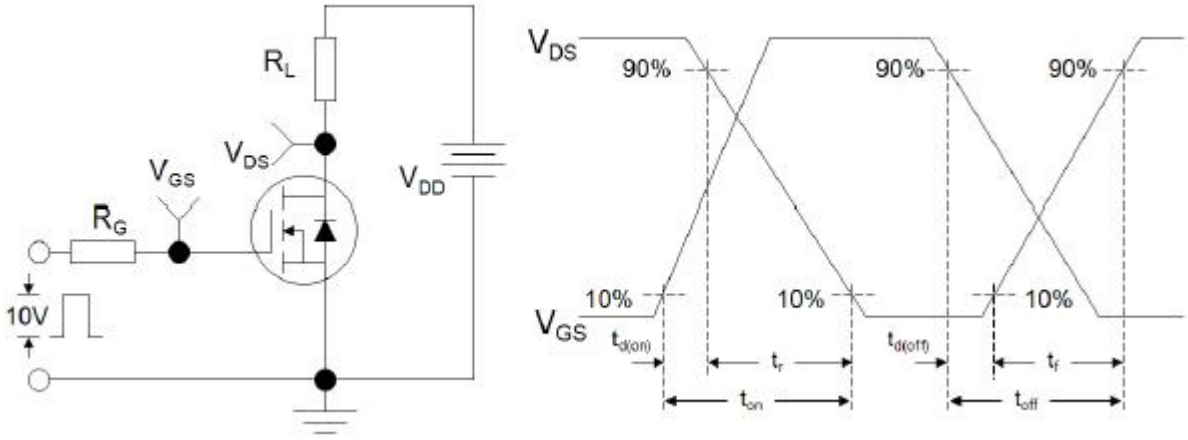


Figure 2: Resistive Switching Test Circuit & Waveforms

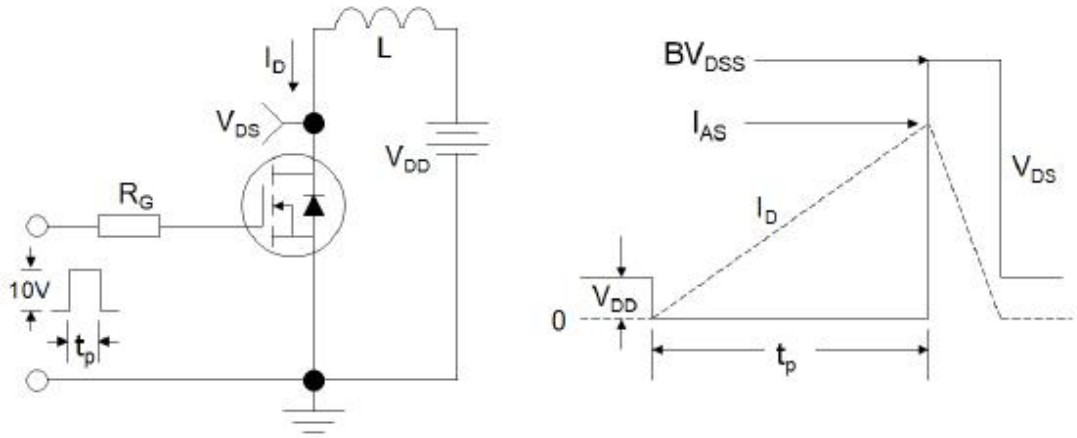
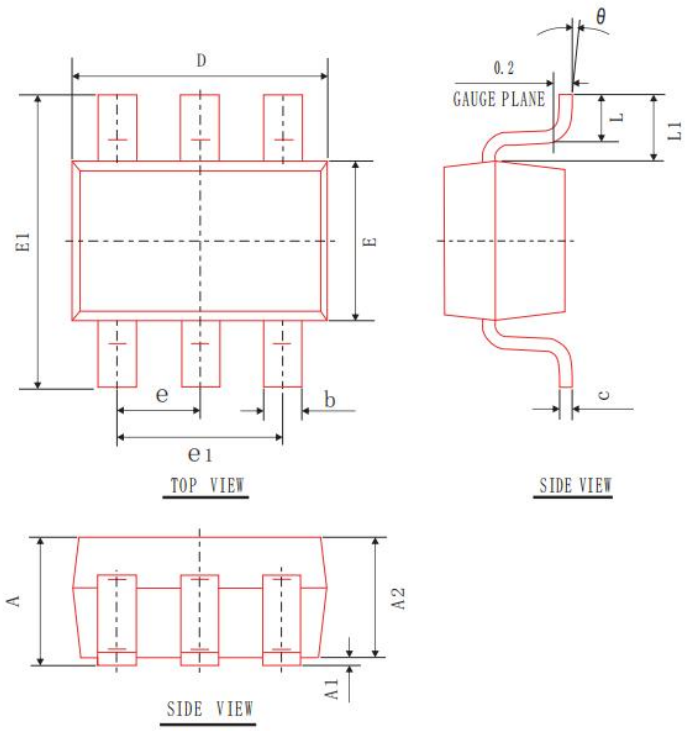


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data-SOT-363-6L



COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	0.05	0.10
A2	0.90	0.95	1.00
b	0.20	0.25	0.30
c	0.08	0.10	0.15
e1	1.20	1.30	1.40
D	2.00	2.10	2.20
E	1.15	1.25	1.35
E1	2.15	2.30	2.45
L	0.26	0.36	0.46
θ	0°	4°	8°
L1	0.525 REF		
e	0.65 TYP		